

Amendments to the Specification:

Please replace paragraph [0033] with the following amended paragraph:

[0033] Alternatively, another method for improving uniformity of a film in PECVD system is shown in the flowchart of Fig. 4. The deposition procedure S30, the cleaning procedure S40 and the pre-deposition procedure S50, which are the same as those of Fig. 2, are sequentially carried out. Then, Step S60 is performed by introducing a specified gas into the deposition chamber 10, thereby diluting contaminants in the deposition chamber 10 and stabilizing a condition such as a temperature of the deposition chamber 10. Then, the deposition chamber 10 is kept idle for a specified period of time so as to stabilize a condition such as temperature distribution of the deposition chamber 10 (Step S70). In such way, the thin film deposited on the first substrate will have an improved uniformity. The sequences for performing Steps S60 and S70 can be exchanged so as to provide an improved uniformity of the first substrate.